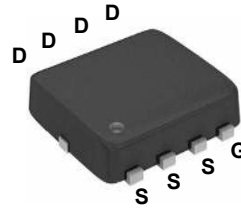
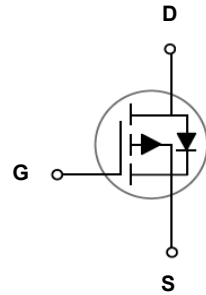


### Main Product Characteristics

$BV_{DSS}$	-20V
$R_{DS(ON)}$	8.3m $\Omega$
$I_D$	-55A



PPAK 3x3



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFP0255 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 10$	V
Drain Current-Continuous ( $T_C=25^\circ\text{C}$ )	$I_D$	-55	A
Drain Current-Continuous ( $T_C=100^\circ\text{C}$ )		-35	
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	-220	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	157	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	-56	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	51	W
Power Dissipation-Derate above 25 $^\circ\text{C}$		0.41	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.45	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-55 To +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 To +150	$^\circ\text{C}$

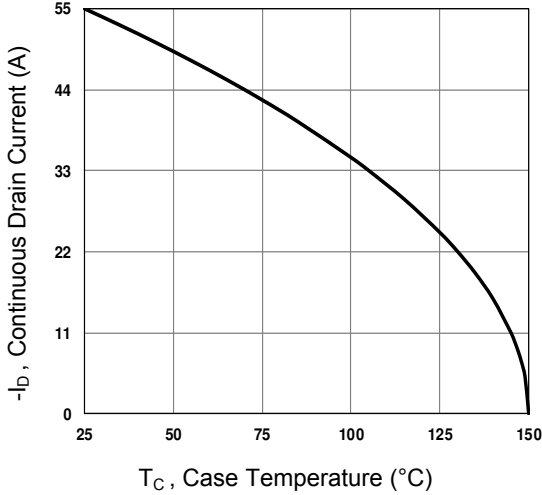
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On/Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	-20	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=-20V, V_{GS}=0V, T_J=25^\circ\text{C}$	-	-	-1	$\mu A$
		$V_{DS}=-16V, V_{GS}=0V, T_J=125^\circ\text{C}$	-	-	-10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 10V, V_{DS}=0V$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-12A$	-	6.9	8.3	m $\Omega$
		$V_{GS}=-2.5V, I_D=-10A$	-	9.4	12	
		$V_{GS}=-1.8V, I_D=-8A$	-	14	18	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-0.3	-0.6	-1	V
Forward Transconductance	$g_{fs}$	$V_{DS}=-10V, I_D=-3A$	-	15	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{DS}=-10V, I_D=-30A, V_{GS}=-4.5V$	-	30	45	nC
Gate-Source Charge <sup>3,4</sup>	$Q_{gs}$		-	4.7	7.1	
Gate-Drain Charge <sup>3,4</sup>	$Q_{gd}$		-	9	13.5	
Turn-On Delay Time <sup>3,4</sup>	$t_{d(on)}$	$V_{DD}=-10V, R_G=6\Omega, V_{GS}=-4.5V, I_D=-30A$	-	15	23	nS
Rise Time <sup>3,4</sup>	$t_r$		-	20	30	
Turn-Off Delay Time <sup>3,4</sup>	$t_{d(off)}$		-	30	55	
Fall Time <sup>3,4</sup>	$t_f$		-	25	38	
Input Capacitance	$C_{iss}$	$V_{DS}=-10V, V_{GS}=0V, F=1\text{MHz}$	-	3300	5000	pF
Output Capacitance	$C_{oss}$		-	420	630	
Reverse Transfer Capacitance	$C_{rss}$		-	370	560	
Gate Resistance	$R_g$	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	-	5	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V, \text{Force Current}$	-	-	-55	A
Pulsed Source Current	$I_{SM}$		-	-	-110	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$	-	-	-1	V

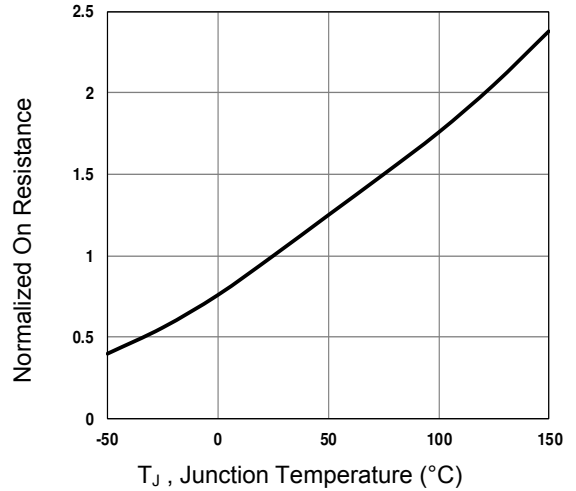
Note:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=-25V, V_{GS}=-10V, L=0.1\text{mH}, I_{AS}=-56A$ , starting  $T_J=25^\circ\text{C}$ .
3. Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

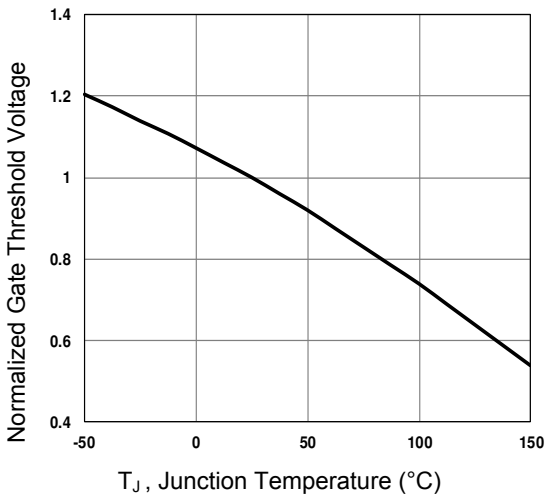
**Typical Electrical and Thermal Characteristic Curves**



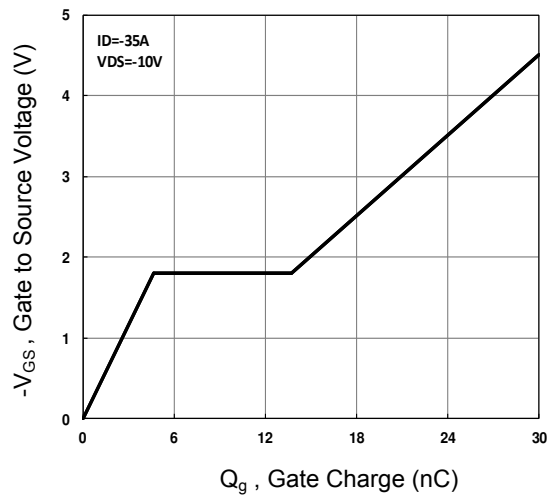
**Figure 1. Continuous Drain Current vs.  $T_C$**



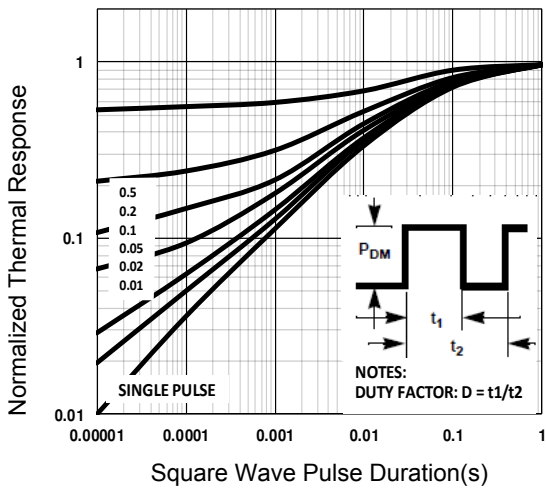
**Figure 2. Normalized  $R_{DS(on)}$  vs.  $T_J$**



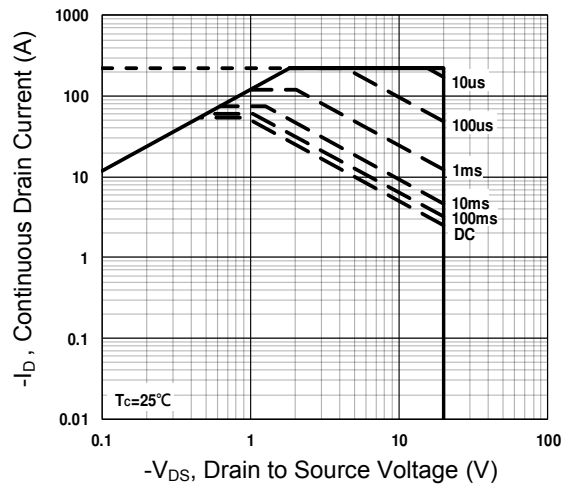
**Figure 3. Normalized  $V_{th}$  vs.  $T_J$**



**Figure 4. Gate Charge Waveform**



**Figure 5. Normalized Transient Impedance**



**Figure 6. Maximum Safe Operation Area**

**Typical Electrical and Thermal Characteristic Curves**

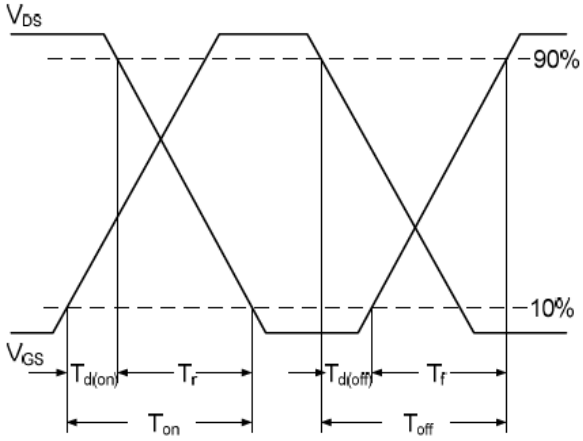


Figure 7. Switching Time Waveform

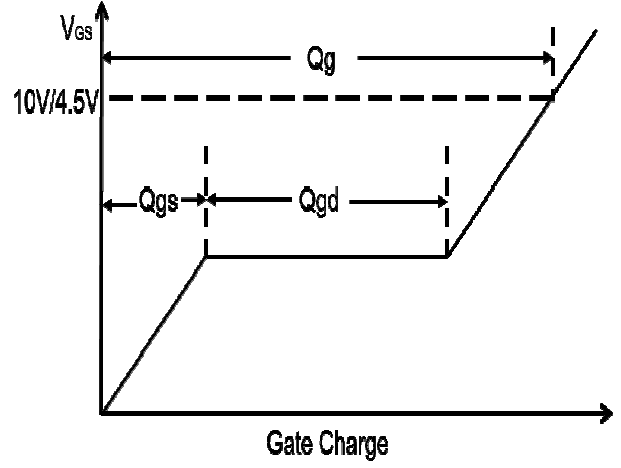
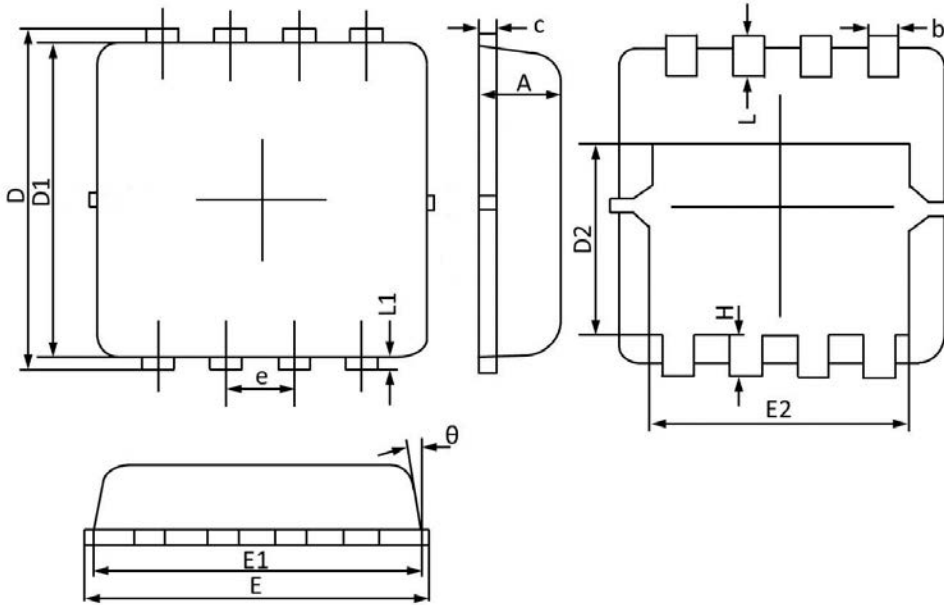


Figure 8. Gate Charge Waveform

**Package Outline Dimensions (PPAK3x3)**



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	0.700	0.900	0.028	0.035
b	0.250	0.350	0.010	0.014
c	0.100	0.250	0.004	0.010
D	3.050	3.500	0.120	0.138
D1	2.900	3.200	0.114	0.126
D2	1.350	1.950	0.053	0.077
E	3.000	3.400	0.118	0.134
E1	2.900	3.300	0.114	0.130
E2	2.350	2.600	0.093	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.750	0.012	0.030
L	0.300	0.600	0.012	0.024
L1	0.060	0.200	0.002	0.008
θ	6°	14°	6°	14°

**Order Information**

Device	Package	Marking	Carrier	Quantity
GSFP0255	PPAK3x3	DC2363C	Tape & Reel	3,000 pcs / Reel